Plaskon SMT-B-1

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

Message:

This material is an epoxy molding compound designed specifically for grid arrays (BGA/LGA). It is formulated with a unique resin system, which minimizes warpage and enables trouble-free molding onto rigid and flexible laminate substrates. Minimal dimensional change after molding, post bake and subsequent solder treatment make this compound an excellent choice for grid arrays.

General Information			
Features	Semi-conductive		
	Good dimensional stability		
	Low warpage		
	High temperature strength		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	**Nominal Value**	**Unit**	**Test Method**
Specific Gravity	1.86	g/cm³	ASTM D792
Molding Shrinkage - Flow	0.050	%	ASTM D955
Mechanical	**Nominal Value**	**Unit**	**Test Method**
Flexural Modulus			ASTM D790
22°C	1.38	MPa	ASTM D790
215°C	0.824	MPa	ASTM D790
Flexural Strength			ASTM D790
22°C	0.0103	MPa	ASTM D790
215°C	0.00363	MPa	ASTM D790
Thermal	**Nominal Value**	**Unit**	**Test Method**
Glass Transition Temperature	225	°C	ASTM E1356
CLTE - Flow	1.4E-5	cm/cm/°C	ASTM D696
Thermal Conductivity	0.70	W/m/K	ASTM C177
Electrical	**Nominal Value**	**Unit**	**Test Method**
Volume Resistivity	1.0E+15	ohms·cm	ASTM D257
Dielectric Strength	16	kV/mm	ASTM D149
Dielectric Constant (1 kHz)	4.00		ASTM D150
Flammability	**Nominal Value**	**Unit**	**Test Method**
Flame Rating (3.18 mm)	V-0		UL 94
Oxygen Index	34	%	ASTM D2863
Additional Information			

Recommended Storage Temperature: <5°CLife @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 24 monthsLife @ 21°C, defined as not more than 40% loss of spiral flow based on original values.: 8 daysLife @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 3 daysSpiral Flow, 175°C, 1000 psi: 77 cmShimadzu Viscosity, 175°C, 1000 psi: 88 poiseRam Follower Gel Time, 175°C, 1000 psi: 19 secAsh Content: 77.4 %Hydrolyzable Halides: <1 ppmCull Hot Hardness, Shore D: 73Volume Resistivity, 22°C: 1e15 ohm-cmVolume Resistivity, 150°C: 1e12 ohm-cmAll test specimens are transfer molded and post cured for 4 hours at 175°C
Linear Thermal Expansion, Alpha 1: 14 cm^-6/cm/°C
Linear Thermal Expansion, Alpha 2: 58 cm^-6/cm/°C

Injection instructions

Resin Transfer Molding:
Molding Temperature: 170 to 185°C
Molding Pressure: 750 to 1250 psi
In Mold Cure Time: 120 to 180 sec
Post Mold Cure Time, 175°C: 4 to 6 hr

Recommended distributors for this material

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